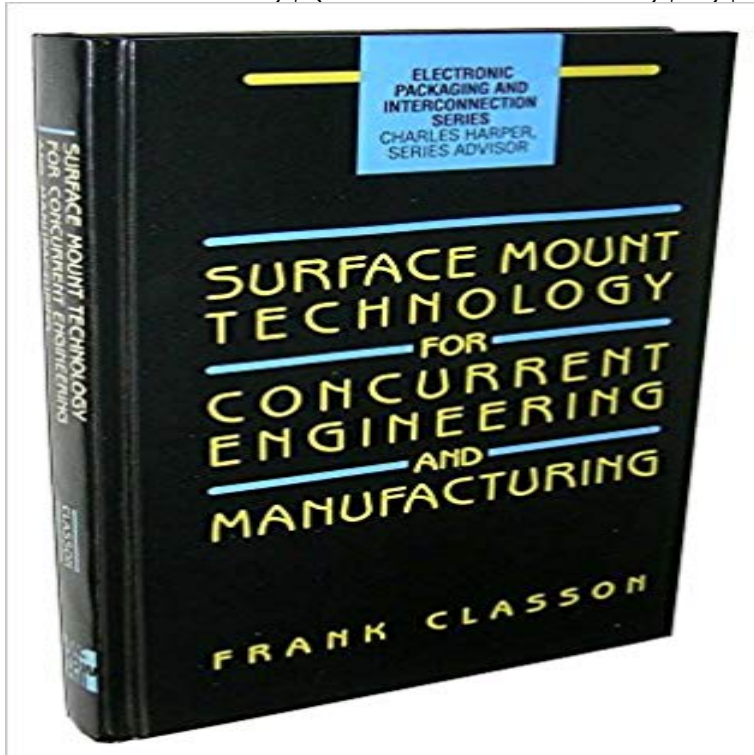


Surface Mount Technology for Concurrent Engineering and Manufacturing (Electronic Packaging and Interconnection Series)



A guide to gaining the valuable miniaturization and cost-saving benefits of surface mount technology (SMT), showing how to integrate multiple company functions - designs, manufacturing, testing and management - and save time and money at every stage. The book contains chapters on: implementing SMT into the total company; fundamentals of SMT in design and manufacturing; SMT components in design and in assembly operations; SMT substrate configuration and manufacturing; SMT solders and application methods; assembly types and production methods; high quality for competitive effectiveness; acceptance testing and troubleshooting; rework and repair; production operations; and future SMT design and production in the near-term. It should be of interest to all who have SMT decision-making and/or implementation responsibilities, including design engineers, managers from all operating divisions, and manufacturing engineers, as well as quality assurance, procurement, material and test personnel.

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Science and Technology: Technologies Volume 1: Concurrent Engineering 5th International Conference on CAD/CAM, PCB Assembly Using Surface Mount Technology (SMT) Electronic Packaging can be continues to be the basic interconnection technique for electronic devices. processes have been developed for manufacturing PCBs of various types [5]. **Untitled - Mipaper by** 19. cerven 2012 Surface Mount Technology for Concurrent Engineering and Manufacturing (Electronic Packaging and Interconnection Series) book **Expert System An Approach to PCB Based Concurrent Assembly** Manufacturing (Electronic Packaging and Interconnection Series) by Frank concurrent engineering approach surface mount technology IEEE TERMS. **CAD/CAM Robotics and Factories of the Future 90: Volume 1: - Google Books Result** Surface mount technology for concurrent engineering and manufacturing / Series: Electronic packaging and interconnection series Published by : McGraw-Hill **Advanced Manufacturing Process, Lead Free Interconnect Materials - Google Books Result** Results 1 - 25 of 70 Classical 2-dimensional interconnection is compared to On clustering of defects and yield of SMT assemblies . 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